

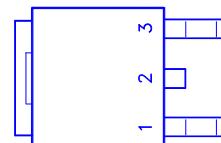
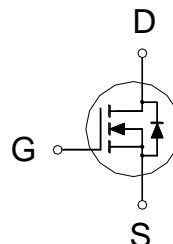
NIKO-SEM**N-Channel Enhancement Mode
Field Effect Transistor****P0460EDA**

TO-252

Halogen-Free & Lead-Free

**PRODUCT SUMMARY**

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
600V	2.5Ω	4A



1. GATE
2. DRAIN
3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Drain-Source Voltage	V_{DS}	600	V
Gate-Source Voltage	V_{GS}	± 30	V
Continuous Drain Current ²	I_D	4	A
		2.5	
Pulsed Drain Current ^{1, 2}	I_{DM}	20	A
Avalanche Current ³	I_{AS}	2	
Avalanche Energy ³	E_{AS}	20	mJ
Power Dissipation	P_D	46	W
		18	
Operating Junction & Storage Temperature Range	T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		2.8	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

¹Pulse width limited by maximum junction temperature.²Limited only by maximum temperature allowed³ $V_{DD} = 50V$, $L = 10mH$, starting $T_J = 25^\circ C$ **ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ C$, Unless Otherwise Noted)**

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	600			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	2.8	4	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 30V$			± 100	nA
Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 600V, V_{GS} = 0V, T_C = 25^\circ C$			1	μA
		$V_{DS} = 480V, V_{GS} = 0V, T_C = 100^\circ C$			10	

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Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 2A$		2	2.5	Ω
Forward Transconductance ¹	g_f	$V_{DS} = 15V, I_D = 2A$		5.5		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		565		pF
Output Capacitance	C_{oss}			62		
Reverse Transfer Capacitance	C_{rss}			6		
Total Gate Charge ²	Q_g	$V_{DD} = 480V, I_D = 4A, V_{GS} = 10V$		14		nC
Gate-Source Charge ²	Q_{gs}			2.5		
Gate-Drain Charge ²	Q_{gd}			5.1		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{GS} = 10V, V_{DD} = 300V,$ $I_D = 4A, R_G = 25\Omega$		18		nS
Rise Time ²	t_r			48		
Turn-Off Delay Time ²	$t_{d(off)}$			47		
Fall Time ²	t_f			50		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)						
Continuous Current ³	I_S			4		A
Forward Voltage ¹	V_{SD}	$I_F = 4A, V_{GS} = 0V$			1	V
Reverse Recovery Time	t_{rr}	$I_F = 4A, dI_F/dt = 100A/\mu S$		341		nS
Reverse Recovery Charge	Q_{rr}			2.1		uC

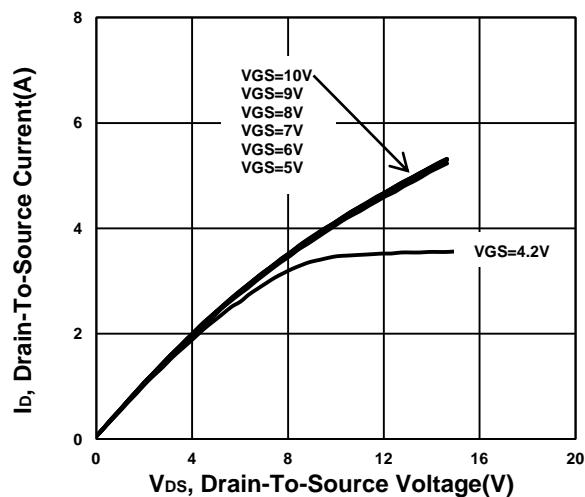
¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.³Pulse width limited by maximum junction temperature.

NIKO-SEM

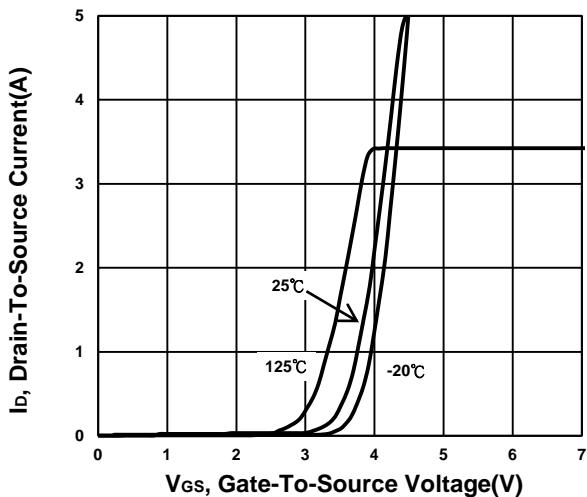
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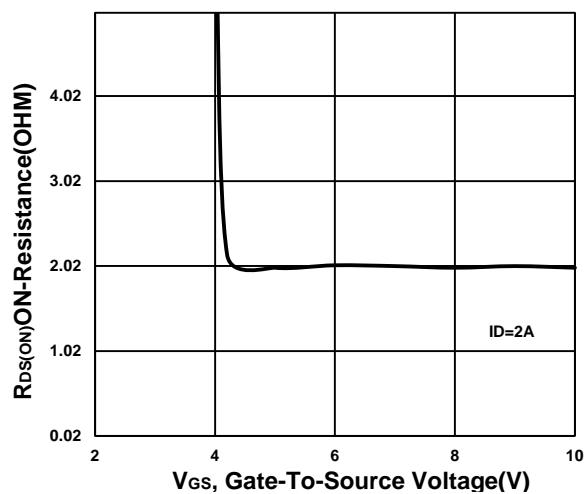
Output Characteristics



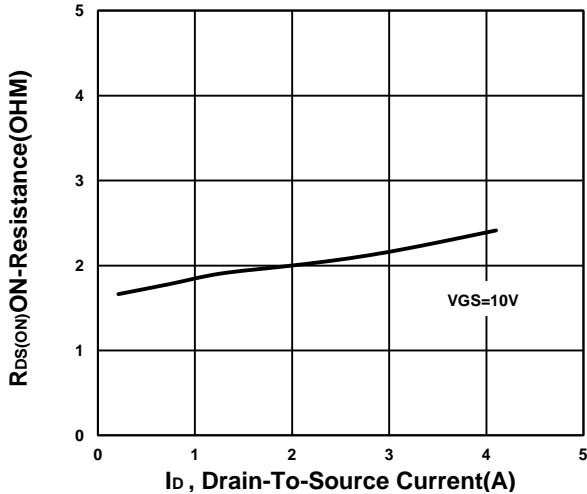
Transfer Characteristics



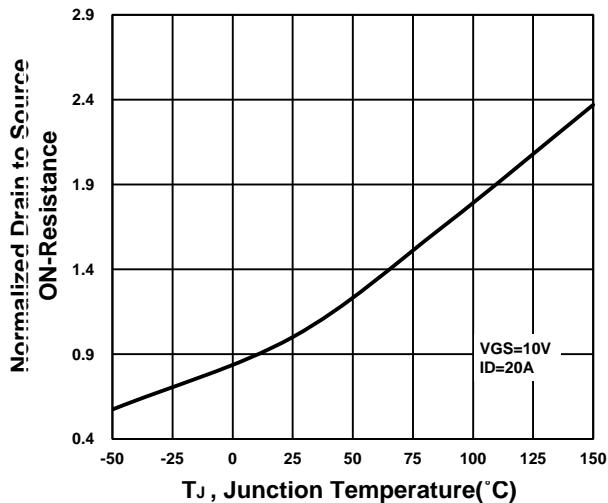
On-Resistance VS Gate-To-Source



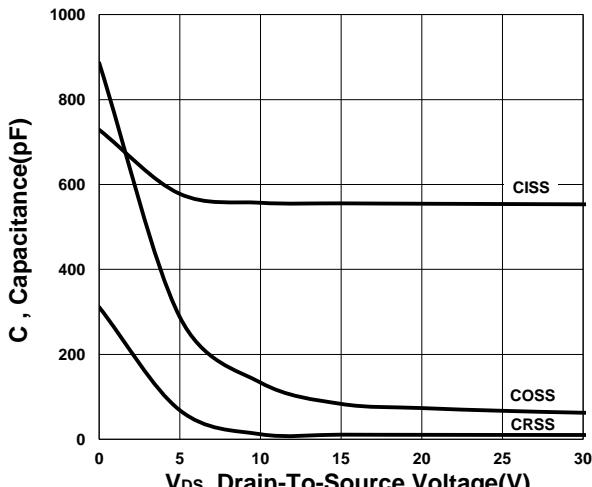
On-Resistance VS Drain Current



On-Resistance VS Temperature



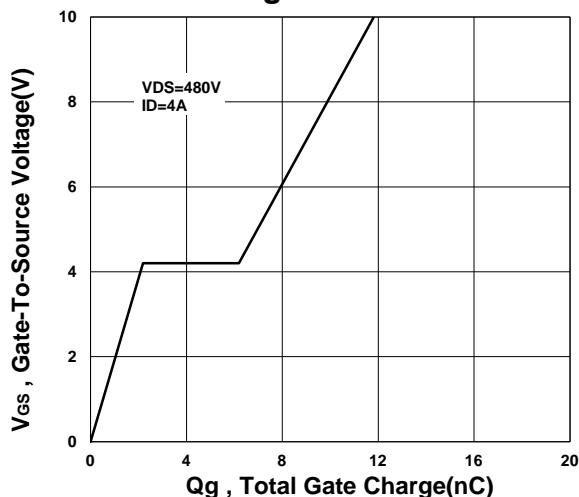
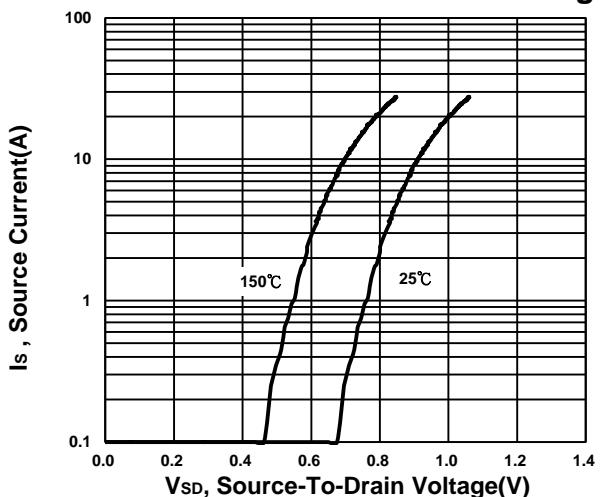
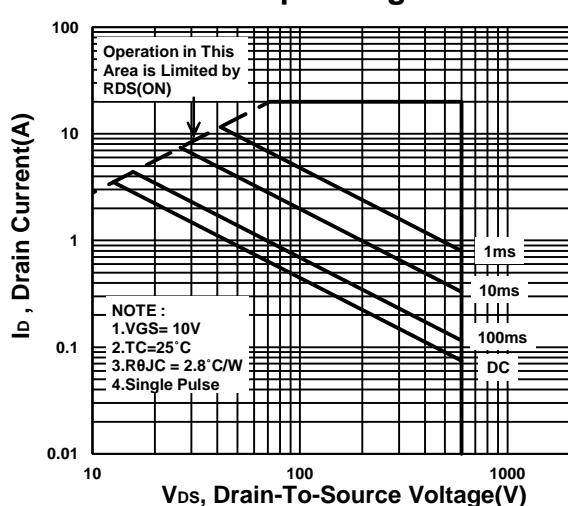
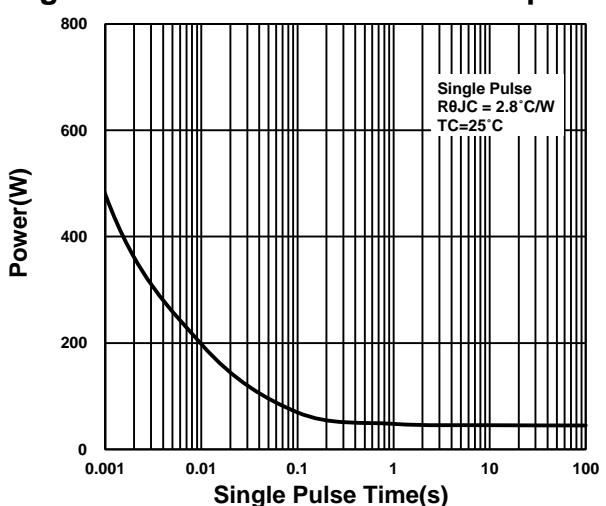
Capacitance Characteristic



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Gate charge Characteristics**Source-Drain Diode Forward Voltage****Safe Operating Area****Single Pulse Maximum Power Dissipation****Transient Thermal Response Curve**